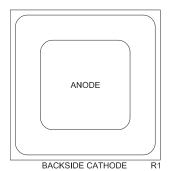


CPD69-CMR1-06

General Purpose Rectifier Die 1.0 Amp, 600 Volt

The CPD69-CMR1-06 is a silicon 1.0 Amp, 600 Volt general purpose rectifier ideal for all types of commercial, industrial, entertainment, and computer applications.



MECHANICAL SPECIFICATIONS:

Die Size	42.5 x 42.5 MILS
Die Thickness	11.0 MILS
Anode Bonding Pad Size	24 x 24 MILS
Top Side Metalization	Ni/Au – 5,000Å/1,350Å
Back Side Metalization	Ni/Au – 5,000Å/1,350Å
Scribe Alley Width	2.76 MILS
Wafer Diameter	4 INCHES
Gross Die Per Wafer	5,915

MAXIMUM RATINGS: (T _A =25°C)	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V_{RRM}	600	V
DC Blocking Voltage	V_{R}	600	V
RMS Reverse Voltage	V _{R(RMS)}	420	V
Average Forward Current (T _A =75°C)	Ìο	1.0	Α
Peak Forward Surge Current, tp=8.3ms	I _{FSM}	30	Α
Operating and Storage Junction Temperature	$T_{\rm J}, T_{\rm sta}$	-65 to +150	°C

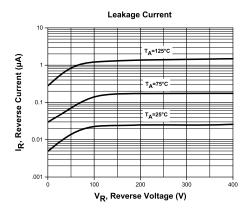
ELECTRICA	AL CHARACTERISTICS: (TA=25	C unless otherwise)		
SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I_{R}	V _R =600V		10	μΑ
V_{F}	I _F =1.0A		1.1	V
C_J	V _R =0, f=1.0MHz		40	pF

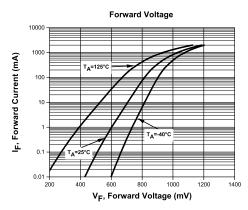
CPD69-CMR1-06

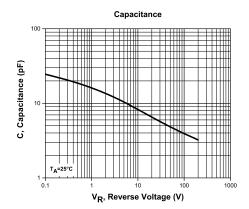
Typical Electrical Characteristics

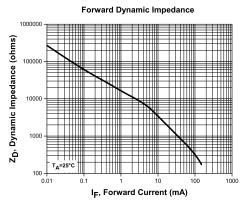


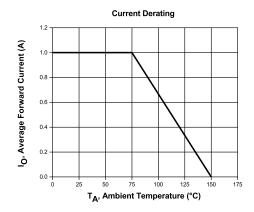
www.centralsemi.com





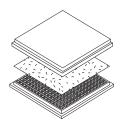






BARE DIE PACKING OPTIONS

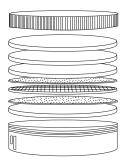




BARE DIE IN TRAY (WAFFLE) PACK

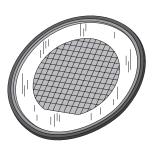
CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes). (example: CP211-PART NUMBER-CM)



UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked. (example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked.

(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications: www.centralsemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- · Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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